

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A substrate processing apparatus, comprising:

a substrate holder capable of holding plural substrates;

a processing chamber which houses the substrates held by the substrate holder;  
and

a heater which heats the processing chamber;

heating means for heating the processing chamber; and

gas supplying means for supplying processing gas to the processing chamber heated by the heating means, thereby processing the substrate,

wherein the substrate holder includes:

at least three support columns provided substantially vertically;

plural substrate mounting portions which mount the plural substrates substantially horizontally at a predetermined interval, the substrate mounting portions being provided at multi-stages on the support columns; and columns so as to protrude from the support columns;

plural ring-like plates arranged which surround the at least three support columns, are provided at multi-stages on the support columns, and provided are provided substantially horizontally at a predetermined interval with respect to the substrates supported on the substrate mounting portions. and

inner circumferential surfaces of the ring-like plates, the inner circumferential surfaces being opposite to the support columns, are notched on a periphery of the support columns.

2. (Currently Amended) The substrate processing apparatus according to claim 1, wherein the substrate mounting portions are columnar-columnar shape or approximately semi-columnar in cross-section shape.

3. (Original) The substrate processing apparatus according to claim 2, wherein the substrate mounting portions are inclined downward toward an inside of the ring-like plates in a diameter direction.

4-5. (Canceled)

6. (Currently Amended) The substrate processing apparatus according to ~~claim 5,~~claim 2, wherein tips of the substrate mounting portions are rounded or chamfered.

7. (Canceled)

8. (Currently Amended) The substrate processing apparatus ~~according to claim 4,~~according to claim 1, wherein the support columns are composed into an approximately semi-columnar ~~shape in cross section,~~shape, and the substrate mounting portions are protruded on a chord side of the support columns.

9. (Original) The substrate processing apparatus according to claim 8, wherein, on the chord side, an inside thereof in a diameter direction of the ring-like plates is scooped out.

10. (Currently Amended) The substrate processing apparatus according to ~~claim 4,~~claim 1, wherein the support columns are provided ~~more inside than so as to run over~~ outer circumferences of the ring-like plates.

11. (Currently Amended) A substrate processing apparatus, comprising:

a substrate holder capable of holding plural substrates;

a processing chamber which houses the substrates held by the substrate ~~holder,~~holder;  
and

a heater which heats the processing chamber;

heating means for heating the processing chamber; and

gas supplying means for supplying processing gas to the processing chamber heated by the heating means, thereby processing the substrate,

wherein the substrate holder includes:

at least three support columns provided substantially vertically; and

plural ring-like plates which surround the at least three support columns, are provided at multi-stages on the support columns, and are provided substantially horizontally at a predetermined interval with respect to the substrates held by the substrate holder, and

inner circumferential surfaces of the ring-like plates, the inner circumferential surfaces being opposite to the support columns, are notched on a periphery of the support columns.

12. (Currently Amended) The substrate processing apparatus according to claim 11, wherein the support columns are composed into an approximately semi-columnar ~~shape in cross-section, shape,~~ and the substrate mounting portions are protruded on a chord side of the support columns.

13. (Currently Amended) The substrate processing apparatus according to claim 11, wherein the support columns are provided ~~more inside than~~ so as to run over outer circumferences of the ring-like plates.

14. (Original) The substrate processing apparatus according to claim 12, wherein, on the chord side, an inside thereof in a diameter direction of the ring-like plates is scooped out.

15. (Currently Amended) A substrate holder capable of holding plural substrates, comprising:

at least three support columns provided substantially vertically;

plural substrate mounting portions which mount the plural substrates substantially horizontally at a predetermined interval, the substrate mounting portions being provided at multi-stages on the support ~~columns, and~~ columns, so as to protrude from the support columns; and

plural ring-like plates ~~arranged which~~ surround the at least three support columns, are provided at multi-stages on the support columns, and provided substantially horizontally at a

predetermined interval with respect to the substrates supported on the substrate mounting ~~portions~~portions.

wherein inner circumferential surfaces of the ring-like plates, the inner circumferential surfaces being opposite to the support columns, are notched on a periphery of the support columns.

16. (Canceled)

17. (Original) A substrate holder capable of holding plural substrates, comprising:

at least three support columns provided substantially vertically; and

plural ring-like plates which surround the at least three support columns, are provided at multi-stages on the support columns, and are provided substantially horizontally at a predetermined interval with respect to the substrates held by the substrate holder,

wherein inner circumferential surfaces of the ring-like plates, the inner circumferential surfaces being opposite to the support columns, are notched on a periphery of the support columns.

18. (Currently Amended) A method of manufacturing a semiconductor device, the method using a substrate processing apparatus including: a substrate holder capable of

holding plural substrates; a processing chamber which houses the substrates held by the substrate holder; ~~heating means for heating a heater which heats~~ the processing chamber; and ~~gas supplying means for supplying a gas supply pipe which supplies~~ processing gas to the processing chamber heated by ~~the heating means, the heater~~, thereby processing the substrate,

~~in which~~wherein the substrate holder includes: at least three support columns provided substantially vertically; plural substrate mounting portions which mount the plural substrates substantially horizontally at a predetermined interval, the substrate mounting portions being provided at multi-stages on the support columns so as to protrude from the support columns; and plural ring-like plates ~~arranged which surround the at least three support columns, are~~

provided at multi-stages on the support columns, and ~~provided are provided~~ substantially horizontally at a predetermined interval with respect to the substrates supported on the substrate mounting portions, and inner circumferential surfaces of the ring-like plates, the inner circumferential surfaces being opposite to the support columns, are notched on a periphery of the support columns, the method ~~comprising the steps of:~~ comprising:

mounting the substrates on the substrate mounting portions of the substrate holder;  
carrying the substrates mounted on the substrate mounting portions of the substrate holder into the processing chamber;

heating the processing chamber by the ~~heating means; and~~ heater; and  
supplying the processing gas to the heated processing ~~chamber; chamber by the gas supply pipe,~~ thereby processing the substrate.

19. (New) The substrate processing apparatus according to claim 1, wherein an open width of the notch is larger than a width of the substrate mounting portion.

20. (New) The substrate processing apparatus according to claim 1, wherein an open width of the notch is larger than an outside diameter of the support columns.

21. (New) The substrate processing apparatus according to claim 1, wherein the notch comprises:

a fitting portion as a hole into which the support columns is fitted; and  
an opening which opens the fitting portion to the inner circumferential direction of the ring-like plate.

22. (New) The substrate processing apparatus according to claim 11, wherein an open width of the notch is larger than an outside diameter of a corresponding support column.

23. (New) The substrate processing apparatus according to claim 11, wherein the notch comprises:

a fitting portion as a hole into which the support columns is fitted; and

an opening which opens the fitting portion to the inner circumferential direction of the ring-like plate.

24. (New) The substrate processing apparatus according to claim 15, wherein an open width of the notch is larger than a width of the substrate mounting portion.

25. (New) The substrate processing apparatus according to claim 15, wherein an open width of the notch is larger than an outside diameter of a corresponding support column.

26. (New) The substrate processing apparatus according to claim 15, wherein the notch comprises:

a fitting portion as a hole into which a corresponding support column is fitted; and

an opening which opens the fitting portion to the inner circumferential direction of the ring-like plate.

27. (New) The substrate processing apparatus according to claim 15, wherein the support columns are provided so as to run over outer circumferences of the ring-like plates.